

MA2C185 (MA185)

Silicon epitaxial planar type

For high-voltage switching circuits, small power rectification

■ Features

- High reverse voltage
- Large output current I_O
- Allowing to insert into a 5 mm pitch hole

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Maximum peak reverse voltage	V_{RM}	250	V
Output current	I_O	200	mA
Repetitive peak forward current	I_{FRM}	625	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Power dissipation (Average)	$P_{D(AV)}$	400	mW
Junction temperature	T_j	175	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 to +175	$^\circ\text{C}$

Note) *: $t = 1 \text{ s}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

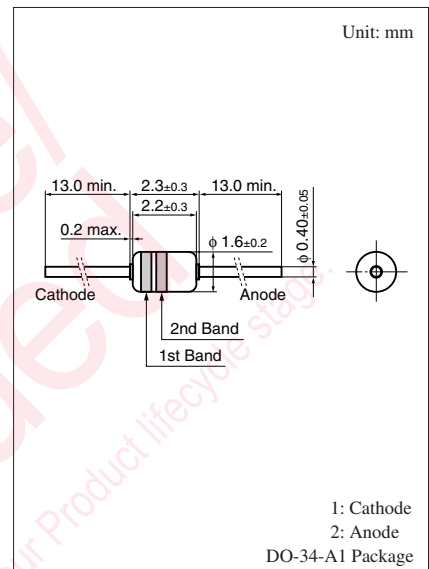
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			1.2	V
Reverse voltage	V_R	$I_R = 100 \mu\text{A}$	250			V
Reverse current	I_R	$V_R = 200 \text{ V}$			200	nA

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

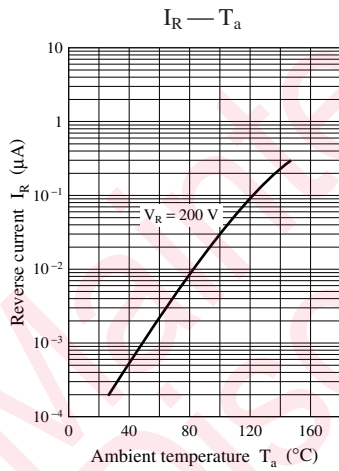
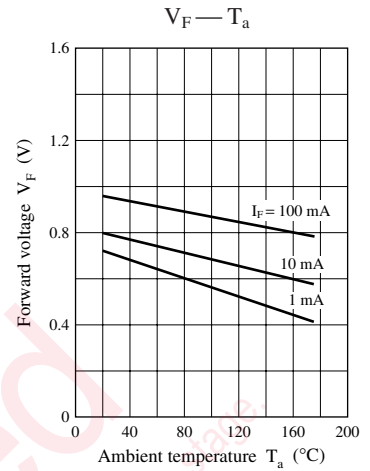
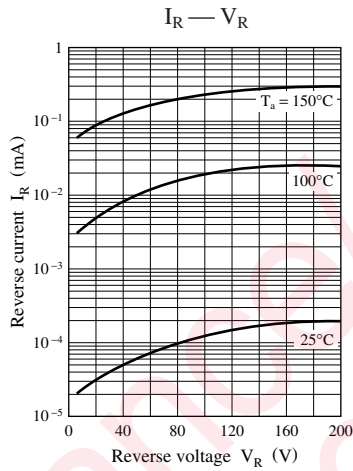
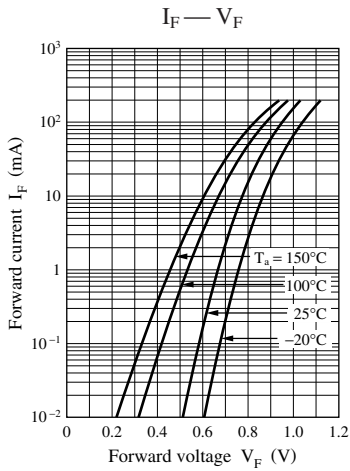
2. Absolute frequency of input and output is 3 MHz.

■ Cathode Indication

Type No.		
Color	1st Band	White
	2nd Band	Green



Note) The part number in the parenthesis shows conventional part number.



Maintenance/Discontinued includes following four Product lifecycle type
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 maintenance type
 planned discontinued type
 discontinued type
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